

1                    **ABSTRACT OF THE DISCLOSURE**

2                    A physical vapor deposition target includes an alloy of copper and  
3                    silver, with the silver being present in the alloy at from less than 1.0  
4                    at% to 0.001 at%. In one implementation, a physical vapor deposition  
5                    target includes an alloy of copper and silver, with the silver being  
6                    present in the alloy at from 50 at% to 70 at%. A physical vapor  
7                    deposition target includes an alloy of copper and tin, with tin being  
8                    present in the alloy at from less than 1.0 at% to 0.001 at%. In one  
9                    implementation, a conductive integrated circuit metal alloy interconnection  
10                  includes an alloy of copper and silver, with the silver being present in  
11                  the alloy at from less than 1.0 at% to 0.001 at%. A conductive  
12                  integrated circuit metal alloy interconnection includes an alloy of copper  
13                  and silver, with the silver being present in the alloy at from 50 at%  
14                  to 70 at%. A conductive integrated circuit metal alloy interconnection  
15                  includes an alloy of copper and tin, with tin being present in the alloy  
16                  at from less than 1.0 at% to 0.001 at%. Other useable copper alloys  
17                  include an alloy of copper and one or more other elements, the one  
18                  or more other elements being present in the alloy at a total  
19                  concentration from less than 1.0 at% to 0.001 at% and being selected  
20                  from the group consisting of Be, Ca, Sr, Ba, Sc, Y, La, Ce, Pr, Nd,  
21                  Pm, Sm, Eu, Gd, Tb, Dy, Ho, Er, Tm, Yb, Lu, Ti, Zr, Hf, Zn, Cd,  
22                  B, Ga, In, C, Se, Te, V, Nb, Ta, Cr, Mo, W, Mn, Tc, Re, Fe, Ru,  
23                  Os, Co, Rh, Ni, Pd, Pt, Au, Tl, and Pb. An electroplating anode is  
24                  formed to comprise one or more of the above alloys.